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May 2014

FDMA8878

Single N-Channel Power Trench[®] MOSFET 30 V, 9.0 A, 16 mΩ

Features

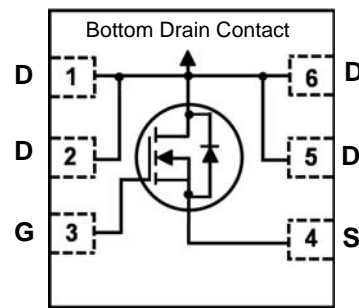
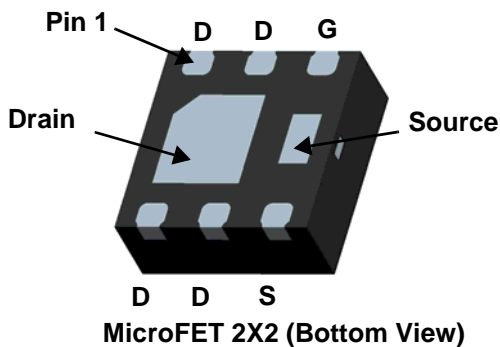
- Max $r_{DS(on)}$ = 16 mΩ at $V_{GS} = 10\text{ V}$, $I_D = 9.0\text{ A}$
- Max $r_{DS(on)}$ = 19 mΩ at $V_{GS} = 4.5\text{ V}$, $I_D = 8.5\text{ A}$
- High performance trench technology for extremely low $r_{DS(on)}$
- Fast switching speed
- RoHS Compliant

General Description

This N-Channel MOSFET is produced using Fairchild Semiconductor's advanced Power Trench[®] process that has been optimized for $r_{DS(on)}$, switching performance.

Application

- DC/DC Buck Converters
- Load Switch in NB
- Notebook Battery Power Management



MOSFET Maximum Ratings $T_A = 25\text{ °C}$ unless otherwise noted

Symbol	Parameter	Ratings	Units
V_{DS}	Drain to Source Voltage	30	V
V_{GS}	Gate to Source Voltage (Note 3)	±20	V
I_D	Drain Current -Continuous (Package Limited) $T_C = 25\text{ °C}$	10	A
	-Continuous $T_A = 25\text{ °C}$ (Note 1a)	9.0	
	-Pulsed	40	
P_D	Power Dissipation $T_A = 25\text{ °C}$ (Note 1a)	2.4	W
	Power Dissipation $T_A = 25\text{ °C}$ (Note 1b)	0.9	
T_J, T_{STG}	Operating and Storage Junction Temperature Range	-55 to +150	°C

Thermal Characteristics

$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1a)	52	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1b)	145	

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
878	FDMA8878	MicroFET 2x2	7"	8 mm	3000 units

Electrical Characteristics $T_J = 25\text{ }^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
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Off Characteristics

BV_{DSS}	Drain to Source Breakdown Voltage	$I_D = 250\text{ }\mu\text{A}$, $V_{GS} = 0\text{ V}$	30			V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	$I_D = 250\text{ }\mu\text{A}$, referenced to $25\text{ }^\circ\text{C}$		26		mV/ $^\circ\text{C}$
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 24\text{ V}$, $V_{GS} = 0\text{ V}$			1	μA
I_{GSS}	Gate to Source Leakage Current, Forward	$V_{GS} = 20\text{ V}$, $V_{DS} = 0\text{ V}$			100	nA

On Characteristics

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}$, $I_D = 250\text{ }\mu\text{A}$	1.2	1.8	3.0	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	$I_D = 250\text{ }\mu\text{A}$, referenced to $25\text{ }^\circ\text{C}$		-5		mV/ $^\circ\text{C}$
$r_{DS(on)}$	Static Drain to Source On Resistance	$V_{GS} = 10\text{ V}$, $I_D = 9.0\text{ A}$		13	16	m Ω
		$V_{GS} = 4.5\text{ V}$, $I_D = 8.5\text{ A}$		16	19	
		$V_{GS} = 10\text{ V}$, $I_D = 9.0\text{ A}$, $T_J = 125\text{ }^\circ\text{C}$		17	21	
g_{FS}	Forward Transconductance	$V_{DD} = 5\text{ V}$, $I_D = 9.0\text{ A}$		41		S

Dynamic Characteristics

C_{iss}	Input Capacitance	$V_{DS} = 15\text{ V}$, $V_{GS} = 0\text{ V}$, $f = 1\text{ MHz}$		539	720	pF
C_{oss}	Output Capacitance			172	230	pF
C_{rss}	Reverse Transfer Capacitance			24	35	pF
R_g	Gate Resistance			1.3		Ω

Switching Characteristics

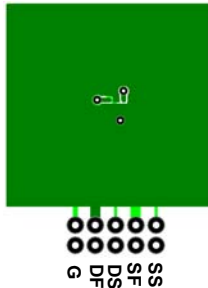
$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 15\text{ V}$, $I_D = 9.0\text{ A}$, $V_{GS} = 10\text{ V}$, $R_{GEN} = 6\text{ }\Omega$		6	12	ns
t_r	Rise Time			2	10	ns
$t_{d(off)}$	Turn-Off Delay Time			14	25	ns
t_f	Fall Time			2	10	ns
$Q_{g(TOT)}$	Total Gate Charge		$V_{GS} = 0\text{ V to }10\text{ V}$		8.5	12
	Total Gate Charge	$V_{GS} = 0\text{ V to }4.5\text{ V}$	$V_{DD} = 15\text{ V}$ $I_D = 9.0\text{ A}$	4.1	5.8	nC
Q_{gs}	Total Gate Charge			1.6		nC
Q_{gd}	Gate to Drain "Miller" Charge			1.2		nC

Drain-Source Diode Characteristics

V_{SD}	Source to Drain Diode Forward Voltage	$V_{GS} = 0\text{ V}$, $I_S = 2.0\text{ A}$ (Note 2)		0.75	1.2	V
		$V_{GS} = 0\text{ V}$, $I_S = 9.0\text{ A}$ (Note 2)		0.86	1.2	
t_{rr}	Reverse Recovery Time	$I_F = 9.0\text{ A}$, $di/dt = 100\text{ A}/\mu\text{s}$		16	28	ns
Q_{rr}	Reverse Recovery Charge			4	10	nC

NOTES:

1. $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta JC}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design.



a. $52\text{ }^\circ\text{C/W}$ when mounted on a 1 in^2 pad of 2 oz copper.



b. $145\text{ }^\circ\text{C/W}$ when mounted on a minimum pad of 2 oz copper.

2. Pulse Test: Pulse Width < $300\text{ }\mu\text{s}$, Duty cycle < 2.0 %.

3. As an N-ch device, the negative Vgs rating is for low duty cycle pulse occurrence only. No continuous rating is implied.

Typical Characteristics $T_J = 25^\circ\text{C}$ unless otherwise noted

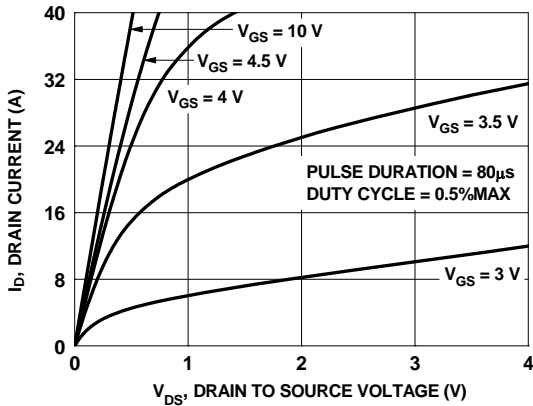


Figure 1. On Region Characteristics

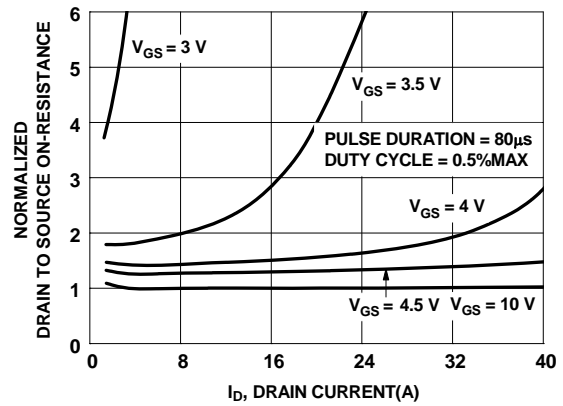


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

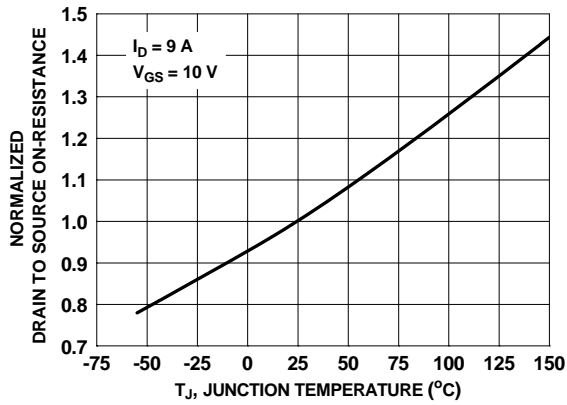


Figure 3. Normalized On Resistance vs Junction Temperature

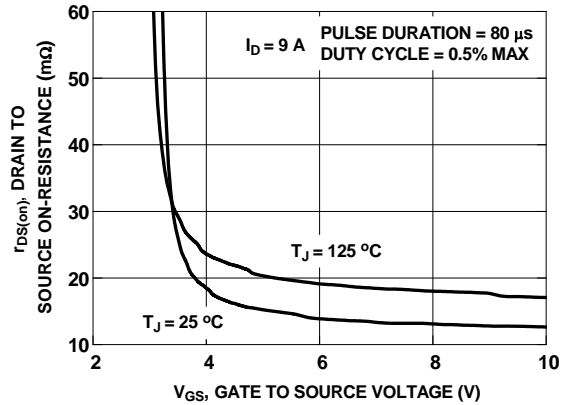


Figure 4. On-Resistance vs Gate to Source Voltage

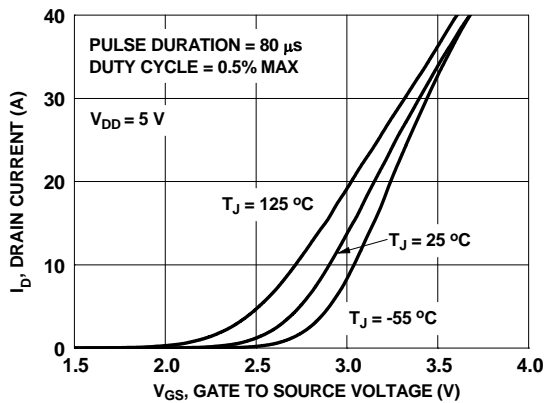


Figure 5. Transfer Characteristics

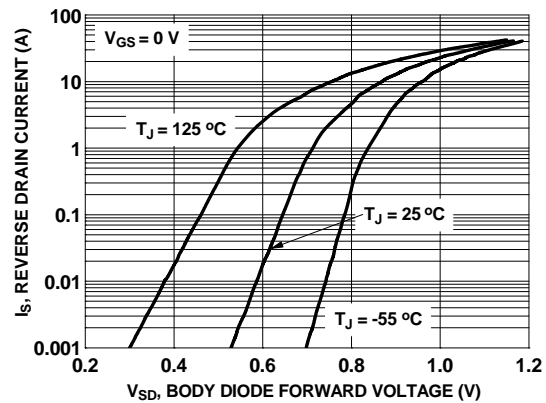


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

Typical Characteristics $T_J = 25^\circ\text{C}$ unless otherwise noted

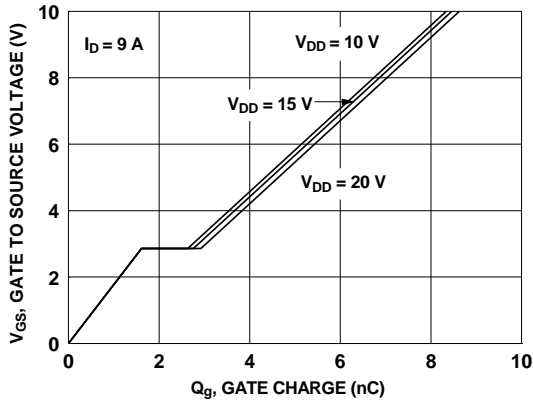


Figure 7. Gate Charge Characteristics

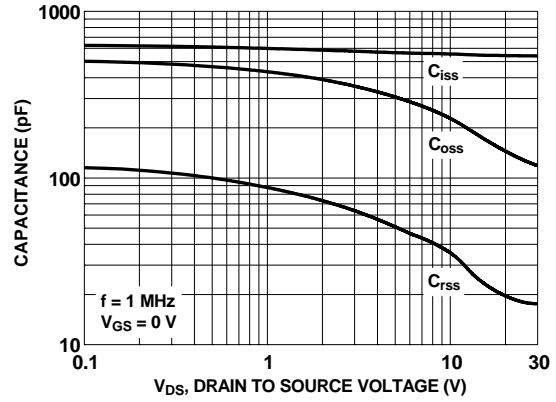


Figure 8. Capacitance vs Drain to Source Voltage

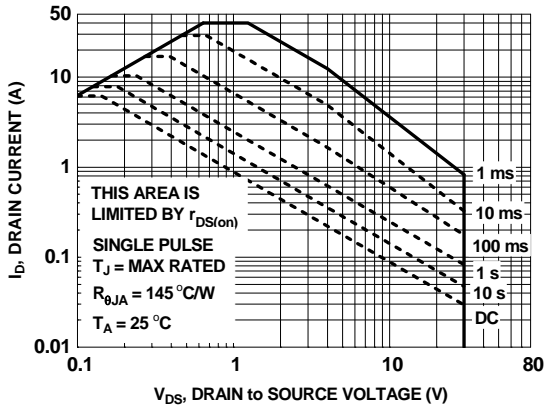


Figure 9. Forward Bias Safe Operating Area

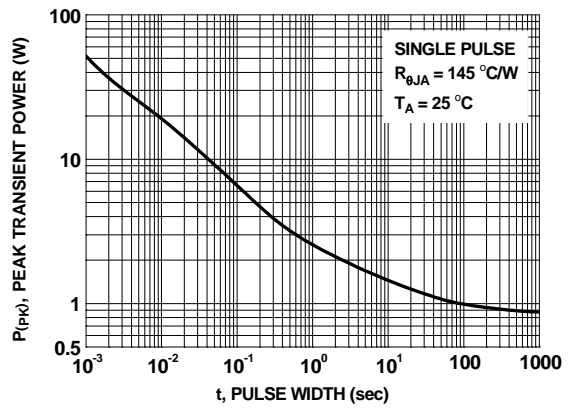


Figure 10. Single Pulse Maximum Power Dissipation

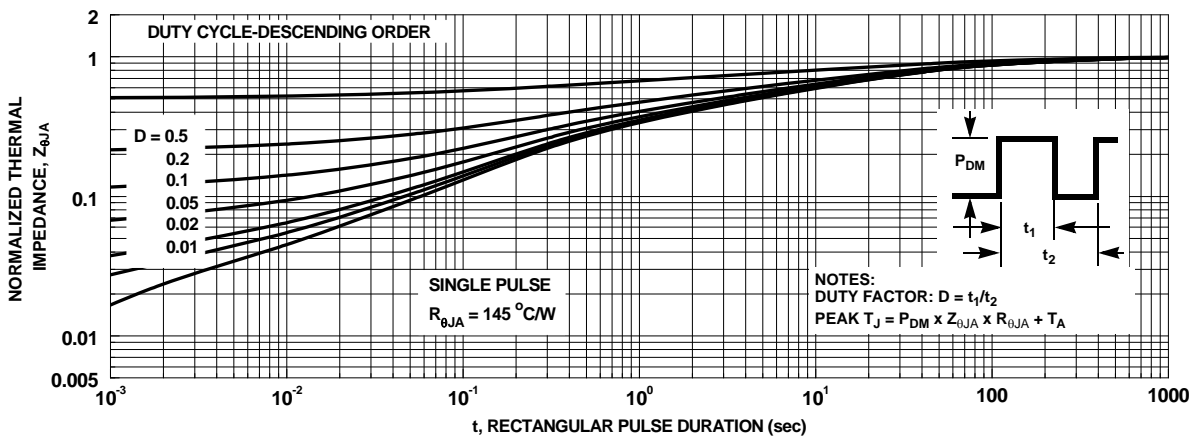
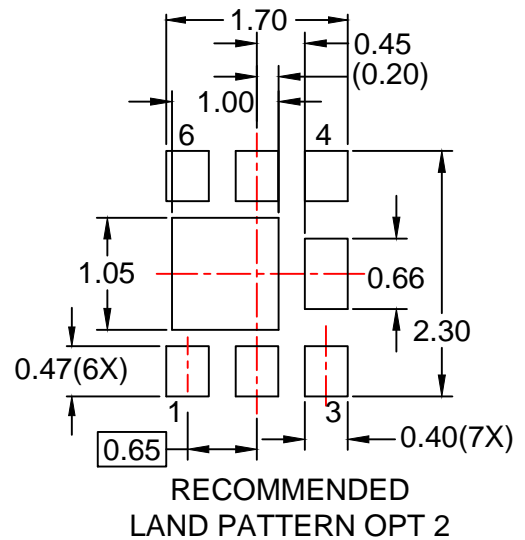
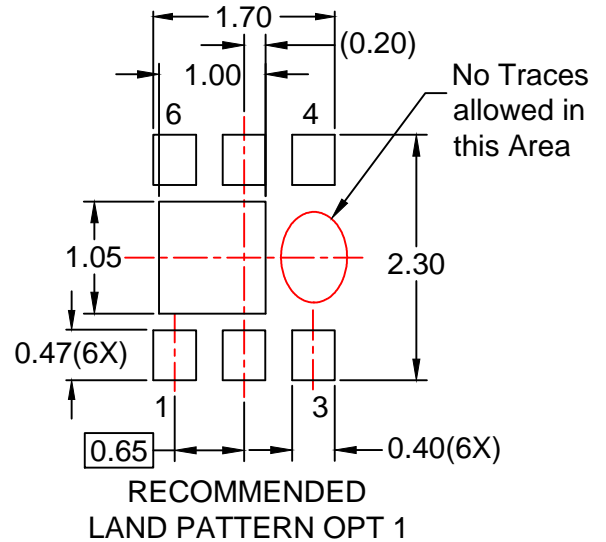
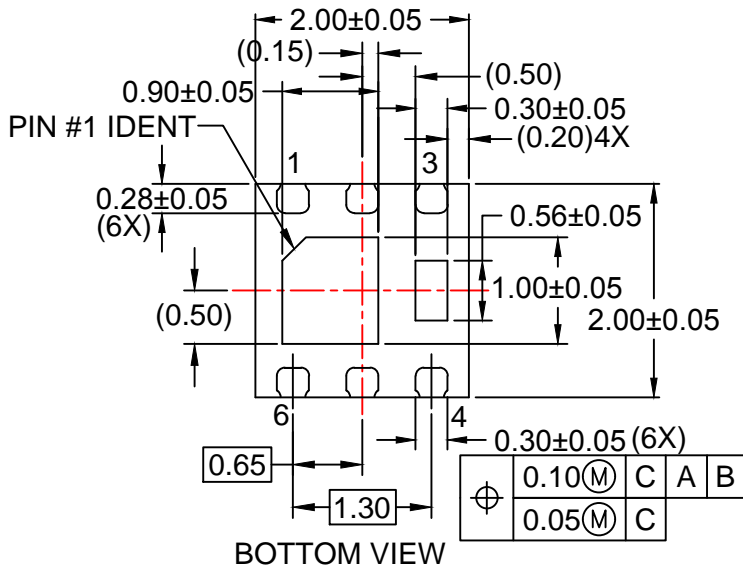
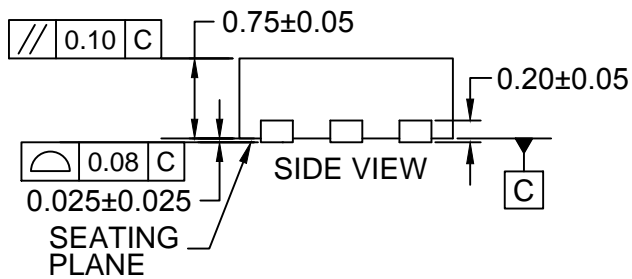
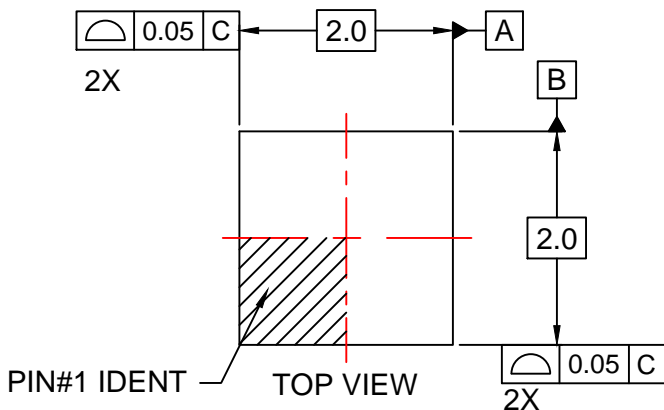


Figure 11. Junction-to-Ambient Transient Thermal Response Curve



NOTES:

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- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 2009.
- D. LAND PATTERN RECOMMENDATION IS EXISTING INDUSTRY LAND PATTERN.
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